



NOTES:

- 1 MATERIAL:
HOUSING: HIGH TEMPERATURE PLASTIC, GLASS FILLED,UL94V-0
TERMINAL:COPPER ALLOY
- 2.PLATING:
SIM CARD CONTACT AREA PLATING: 30u* MIN GOLD OVER 50u*MIN NICKEL PLATING
PCB SOLDERING AREA PLATING:120u* MIN TIN-LEAD OVER 50u*MIN NICKEL PLATING
VISIBLE AREA PLATING: GOLD FLASH OVER 50u* MIN NICKEL PLATING
- 3.PACKAGING:TAPE REEL
- 4.PRODUCT SPECIFICATION:PS-67687-001

EC NO: SH2003-0031 DRWN: SSUN 2003/04/07 CHK: CHIK APPR: SHUANG 2003/04/07	QUALITY SYMBOLS ▽ - 0 ▽ - 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	REVISE ON CAD ONLY	
		mm	INCH	DIMENSION STYLE		TITLE		
		4 PLACES ± ---	± ---	MM ONLY		SIM CARD CONNECTOR SALES DRAWING		
		3 PLACES ± ---	± ---	DRAWN BY SSUN	DATE 2002/07/30	MOLEX INCORPORATED		
2 PLACES ± 0.2	± ---	CHECKED BY LZHAO	DATE 2002/07/30					
1 PLACE ± 0.25	± ---	ANGULAR ± 3 °		APPROVED BY SAMHUANG	DATE 2002/07/30	MATERIAL NO. 676872001	DOCUMENT NO. SD-67687-201	SHEET NO. 1 OF 1
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						